

# 3D IC Market: Trends, Opportunities and Competitive Analysis [2023-2028]

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## Abstracts

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### 3D IC Market Trends and Forecast

The future of the global 3D IC market looks promising with opportunities in the consumer electronics, telecommunication, automotive, military & aerospace, medical device, and industrial markets. The global 3D IC market is expected to reach and estimated \$18.1 billion by 2028 with a CAGR of 25.0% from 2023 to 2028. The major drivers for this market are increasing demand for advanced electronic products and growing application IOT by various end user verticals.

### 3D IC Market by Product, Component, Application, and End Use Industry

A more than 150-page report is developed to help in your business decisions. A sample figure with some insights is shown below.

### 3D IC Market by Segments

### 3D IC Market by Segment

The study includes trends and forecast for the global 3D IC market by product, component, application, end use industry, region, as follows:

3D IC Market by Product [Value (\$B) Shipment Analysis from 2017 to 2028]:

### Stacked 3D

Monolithic 3D

3D IC Market by Component [Value (\$B) Shipment Analysis from 2017 to 2028]:

Through-Silicon Via (TSV)

Through Glass Via (TGV)

Silicon Interposer

3D IC Market by Application [Value (\$B) Shipment Analysis from 2017 to 2028]:

Logic

Imaging & optoelectronics

Memory

MEMS/Sensors

LED

3D IC Market by End Use Industry [Value (\$B) Shipment Analysis from 2017 to 2028]:

Consumer Electronics

Telecommunication

Automotive

Military & Aerospace

Medical Devices

Industrial

3D IC Market by Region [Value (\$B) Shipment Analysis from 2017 to 2028]:

North America

Europe

Asia Pacific

The Rest of the World

List of 3D IC Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies, 3D IC companies cater to increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the 3D IC companies profiled in this report include-

United Microelectronics Corporation

Tezzaron Semiconductor

3M

IBM Corporation

Xilin

Monolithic 3D

Intel Corporation

Toshiba Corp

Amkor Technology

Samsung Electronic

3D IC Market Insights

Lucintel forecasts that stacked 3D will remain the larger segment over the forecast period because it is highly demanded in AI, machine learning, and data center applications.

Consumer electronics is expected to witness the highest growth segment due to increasing demand for portable devices, such as tablets, smartphones, and laptops.

The Asia Pacific region is expected to witness the highest growth during the forecast period due to strong manufacturing capabilities and growing demand from various applications, such as automotive and consumer electronics.

### Features of the 3D IC Market

Market Size Estimates: 3D IC market size estimation in terms of value (\$B)

Trend And Forecast Analysis: Market trends (2017-2022) and forecast (2023-2028) by various segments and regions.

Segmentation Analysis: 3D IC market size by various segments, such as product, component, application, end use industry, and region

Regional Analysis: 3D IC market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis on growth opportunities in different products, components, applications, end use industries, and regions for the 3D IC market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the 3D IC market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

### FAQ

Q1. What is the 3D IC market size?

Answer: The global 3D IC market is expected to reach an estimated \$18.1 billion by 2028.

Q2. What is the growth forecast for 3D IC market?

Answer: The global 3D IC market is expected to grow with a CAGR of 25.0% from 2023 to 2028.

Q3. What are the major drivers influencing the growth of the 3D IC market?

Answer: The major drivers for this market are increasing demand for advanced electronic products and growing application IOT by various end user verticals.

Q4. What are the major segments for 3D IC market?

Answer: The future of the 3D IC market looks promising with opportunities in the consumer electronics, telecommunication, automotive, military & aerospace, medical device, and industrial markets.

Q5. Who are the key 3D IC companies?

Answer: Some of the key 3D IC companies are as follows:

United Microelectronics

Tezzaron Semiconductor

3M

IBM Corporation

Xilin

Monolithic 3D

Intel Corporation

Toshiba Corp

Amkor Technology

Samsung Electronic

Q7. Which 3D IC segment will be the largest in future?

Answer: Lucintel forecasts that stacked 3D will remain the larger segment over the forecast period because it offers better thermal management, and it allows integration of different types of IC, such as processors, memory, and sensors.

Q8. In 3D IC market, which region is expected to be the largest in next 5 years?

Answer: The Asia Pacific region is expected to witness the highest growth during the forecast period due to strong manufacturing capabilities and growing demand from various applications, such as automotive and consumer electronics.

Q9. Do we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1. What are some of the most promising, high-growth opportunities for the 3D IC market by product (stacked 3D and monolithic 3D), component (through-silicon via (TSV), through glass via (TGV), and silicon interposer), application (logic, imaging & optoelectronics, memory, mems/sensors, and led), end use industry (consumer electronics, telecommunication, automotive, military & aerospace, medical devices, and industrial), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2. Which segments will grow at a faster pace and why?

Q.3. Which region will grow at a faster pace and why?

Q.4. What are the key factors affecting market dynamics? What are the key challenges and business risks in this market?

Q.5. What are the business risks and competitive threats in this market?

Q.6. What are the emerging trends in this market and the reasons behind them?

Q.7. What are some of the changing demands of customers in the market?

Q.8. What are the new developments in the market? Which companies are leading these developments?

Q.9. Who are the major players in this market? What strategic initiatives are key players pursuing for business growth?

Q.10. What are some of the competing products in this market and how big of a threat do they pose for loss of market share by material or product substitution?

Q.11. What M&A activity has occurred in the last five years and what has its impact been on the industry?

For any questions related to 3D IC market or related 3D IC companies, 3D IC market size, 3D IC market share, 3D IC analysis, write Lucintel analyst at email: [helpdesk@lucintel.com](mailto:helpdesk@lucintel.com) we will be glad to get back to you soon.

## Contents

### **1. EXECUTIVE SUMMARY**

### **2. GLOBAL 3D IC MARKET: MARKET DYNAMICS**

2.1: Introduction, Background, and Classifications

2.2: Supply Chain

2.3: Industry Drivers and Challenges

### **3. MARKET TRENDS AND FORECAST ANALYSIS FROM 2017 TO 2028**

3.1: Macroeconomic Trends (2017-2022) and Forecast (2023-2028)

3.2: Global 3D IC Market Trends (2017-2022) and Forecast (2023-2028)

3.3: Global 3D IC Market by Product

3.3.1: Stacked 3D

3.3.2: Monolithic 3D

3.4: Global 3D IC Market by Component

3.4.1: Through-Silicon via (TSV)

3.4.2: Through Glass via (TGV)

3.4.3: Silicon Interposer

3.5: Global 3D IC Market by Application

3.5.1: Logic

3.5.2: Imaging & optoelectronics

3.5.3: Memory

3.5.4: MEMS/Sensors

3.5.5: LED

3.6: Global 3D IC Market by End Use Industry

3.6.1: Consumer Electronics

3.6.2: Telecommunication

3.6.3: Automotive

3.6.4: Military & Aerospace

3.6.5: Medical Devices

3.6.6: Industrial

### **4. MARKET TRENDS AND FORECAST ANALYSIS BY REGION FROM 2017 TO 2028**

4.1: Global 3D IC Market by Region



## 4.2: North American 3D IC Market

4.2.1: North American 3D IC Market by Product: Stacked 3D and Monolithic 3D

4.2.2: North American 3D IC Market by End Use Industry: Consumer Electronics, Telecommunication, Automotive, Military & Aerospace, Medical Devices, and Industrial

## 4.3: European 3D IC Market

4.3.1: European 3D IC Market by Product: Stacked 3D and Monolithic 3D

4.3.2: European 3D IC Market by End Use Industry: Consumer Electronics, Telecommunication, Automotive, Military & Aerospace, Medical Devices, and Industrial

## 4.4: APAC 3D IC Market

4.4.1: APAC 3D IC Market by Product: Stacked 3D and Monolithic 3D

4.4.2: APAC 3D IC Market by End Use Industry: Consumer Electronics, Telecommunication, Automotive, Military & Aerospace, Medical Devices, and Industrial

## 4.5: ROW 3D IC Market

4.5.1: ROW 3D IC Market by Product: Stacked 3D and Monolithic 3D

4.5.2: ROW 3D IC Market by End Use Industry: Consumer Electronics, Telecommunication, Automotive, Military & Aerospace, Medical Devices, and Industrial

## 5. COMPETITOR ANALYSIS

5.1: Product Portfolio Analysis

5.2: Operational Integration

5.3: Porter's Five Forces Analysis

## 6. GROWTH OPPORTUNITIES AND STRATEGIC ANALYSIS

6.1: Growth Opportunity Analysis

6.1.1: Growth Opportunities for the Global 3D IC Market by Product

6.1.2: Growth Opportunities for the Global 3D IC Market by Component

6.1.3: Growth Opportunities for the Global 3D IC Market by Application

6.1.4: Growth Opportunities for the Global 3D IC Market by End Use Industry

6.1.5: Growth Opportunities for the Global 3D IC Market by Region

6.2: Emerging Trends in the Global 3D IC Market

6.3: Strategic Analysis

6.3.1: New Product Development

6.3.2: Capacity Expansion of the Global 3D IC Market

6.3.3: Mergers, Acquisitions, and Joint Ventures in the Global 3D IC Market

6.3.4: Certification and Licensing

## 7. COMPANY PROFILES OF LEADING PLAYERS

- 7.1: Tezzaron Semiconductor
- 7.2: 3M Company Besang
- 7.3: IBM Corporation
- 7.4: Xilin
- 7.5: Monolithic 3D
- 7.6: Intel Corporation
- 7.7: Toshiba Corp
- 7.8: Amkor Technology
- 7.9: Samsung Electronic

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